

S/N: Unknown

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants:	Biswajit Sur et al.	Examiner:	Unknown
Serial No.:	Unknown	Group Art Unit:	Unknown
Filed:	Unknown	Docket No.:	884.319US2
Title:	ELECTRONIC ASSEMBLY COMPRISING SOLDERABLE THERMAL INTERFACE AND METHODS OF MANUFACTURE		
Assignee:	Intel Corporation	Customer No.	21186

---

**COMMUNICATION REGARDING SUBMISSION  
OF DIVISIONAL APPLICATION  
UNDER 37 C.F.R. 1.53(b)**

MS Patent Application  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Prior to taking up the above-identified patent application for examination, please consider the Remarks appearing below.

**REMARKS**

No claims have been amended, canceled, or added. As a result, claims 1-29 are pending in this application.

**Divisional Application**

The present application is a divisional of application U.S. Serial No. 09/652,430, filed on August 31, 2000, for which a Notice of Allowance was issued on November 7, 2003.

**Amendments to the Specification**

The present application, as filed, incorporates certain amendments to the specification with respect to the specification of the above-mentioned parent application U.S. Serial No. 09/652,430, as allowed.

Specifically, the present application is prefaced with a new section entitled "Divisional Application".

On page 1, line 14, the words "embodiments of" have been inserted before "the present invention", and "relate" has been substituted for "relates".

In the section entitled "Detailed Description", the sentence "Such embodiments of the inventive subject matter may be referred to, individually and/or collectively, herein by the term "invention" merely for convenience and without intending to voluntarily limit the scope of this application to any single invention or inventive concept if more than one is in fact disclosed." has been added before the last sentence of the first paragraph.

No new matter has been introduced by way of these amendments to the specification of the above-mentioned parent application U.S. Serial No. 09/652,430, as allowed.

**Claims 1-29**

For the Examiner's convenience, the relationship of the claims in the present application to the non-elected originally-filed claims and to certain of the allowed claims of the parent application U.S. Serial No. 09/652,430 will now be briefly discussed.

Claims 1-16, 19-22, and 25-27 of the present application are based upon the indicated non-elected original claims of the parent application according to the table appearing below.

Claims 17-18, 23-25, and 28-29 of the present application are based upon the indicated allowed claims of the parent application according to the table appearing below.

**COMMUNICATION REGARDING SUBMISSION OF DIVISIONAL APPLICATION UNDER 37 C.F.R. 1.53(b)**

Page 4

Serial Number: Unknown

Dkt: 884.319US2 (INTEL)

Filing Date: Unknown

Title: ELECTRONIC ASSEMBLY COMPRISING SOLDERABLE THERMAL INTERFACE AND METHODS OF MANUFACTURE

Assignee: Intel Corporation

Present Application	Parent Application Original Claim	Parent Application Allowed Claim
1	24	
2	25	
3	26	
4	27	
5	28	
6	29	
7	30	
8	27	
9	7	
10	7	
11	28	
12	29	
13	2	
14	3	
15	30	
16	5	
17		6
18		7
19	27	
20	7	
21	7	
22	3	
23		6
24		7
25	27	45
26	7	
27	7	
28		6
29		7

All of the claims are supported by the original disclosure. No new matter has been introduced.

**Conclusion**

Consideration of claims 1-29 is respectfully requested. The Examiner is invited to telephone Applicants' attorney, Walter W. Nielsen (located in Phoenix, Arizona) at (602) 298-8920, or the below-signed attorney (located in Minneapolis, Minnesota) to facilitate prosecution of this application.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743

BISWAJIT SUR ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.  
Attorneys for Intel Corporation  
P.O. Box 2938  
Minneapolis, Minnesota 55402  
612-349-9592

Date Feb. 6, 2004

By Ann M. McCrackin

Ann M. McCrackin  
Reg. No. 42,858

"Express Mail" mailing label number: EV370238909US

Date of Deposit: February 9 2004

This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to the Commissioner for Patents, Mail Stop Patent Application, P.O. Box 1450, Alexandria, VA 22313-1450.